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# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

PUBLICATION NUMBER : 05029534  
PUBLICATION DATE : 05-02-93

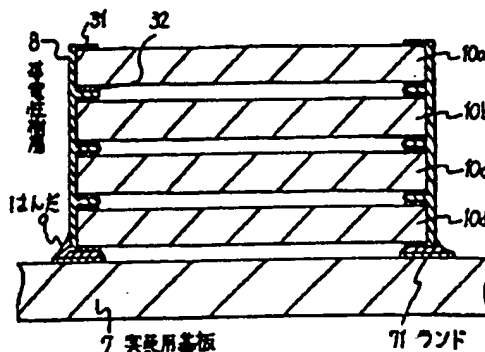
APPLICATION DATE : 25-07-91  
APPLICATION NUMBER : 03185957

APPLICANT : NEC CORP;

INVENTOR : NAKAMURA SHIGEMI;

INT.CL : H01L 25/00

TITLE : MEMORY MODULE



ABSTRACT : PURPOSE: To reduce the external dimension of a memory module by constituting a memory package structure in a leadless chip carrier (LCC) type, and stacking said packages.

CONSTITUTION: A memory package is constituted as an LCC type structure wherein a plurality of first terminals for a common signal and a plurality of second terminals for a characteristic signal, are formed. A plurality of memory packages 10a-10d having the above structure are stacked in the manner in which the characteristic signal is transmitted to each of the memory packages 10a-10d via the mutually different paths of the second terminals, and connected and fixed with a mounting board 7.

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